

**In the Specification**

Please replace the title of the invention with --APPARATUS FOR POSITIONING BACK-UP PINS ON A SUPPORT PLATE FOR SUPPORTING SUBSTRATE--.

Please amend the Abstract as detailed herein:

An apparatus and ~~method~~ for allocating and positioning back-up pins for supporting a substrate are provided. The apparatus includes a substrate guide rail for guiding a circuit board to a predetermined position; a plurality of magnetic back-up pins for supporting the circuit board; a back-up pin plate for placing the back-up pins thereon; a back-up pin stand disposed near the back-up pin plate and for holding the back-up pins; a camera for photographing an image of a surface of the circuit board; a display means for displaying a virtual or composed image of the entire circuit board scanned by the camera and a real-time image of a portion of the circuit board for aiding a user to allocate the adequate support locations of the circuit board; and a transfer means for transferring the back-up pins onto the allocated locations on the back-up pin plate.

Please amend paragraph [00031] of the specification as detailed herein:

[00031] FIG. 4 is an enlarged perspective view of the small-diameter back-up pin 28 29. A circumferential groove 42 is similarly formed at an intermediate location of the small-diameter back-up pin 28 to prevent the small-diameter back-up pin 28 from escaping from the gripper 23 of FIG. 1 when the gripper 23 grips the small-diameter back-up pin 28. The upper portion of the small-diameter back-up pin 28 is smaller than that of the upper portion of the large-diameter back-up pin 29. The upper portion of the small-diameter back-up pin 28 generally has a cylindrical shape with a diameter of about 2 mm. Like the large-diameter back-up pin 29, a marking 43 is formed on a top surface of the small-diameter back-up pin 28, and a magnet portion 41 is provided at a lower portion thereof for the reasons described above.